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Li et al.

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(54) **VERTICAL TUNNEL FIELD EFFECT TRANSISTOR**

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H01L 29/78 (2006.01)

H01L 29/739 (2006.01)

(52) **U.S. Cl.**

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(58) **Field of Classification Search**

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USPC 257/105

See application file for complete search history.

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Primary Examiner — Monica D Harrison

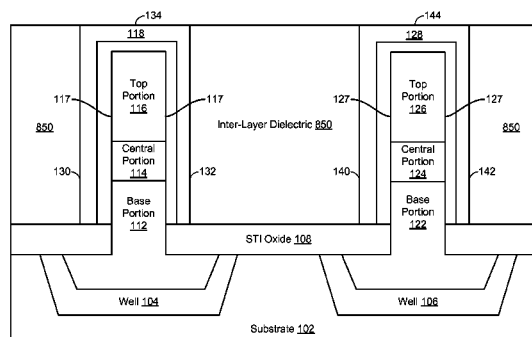
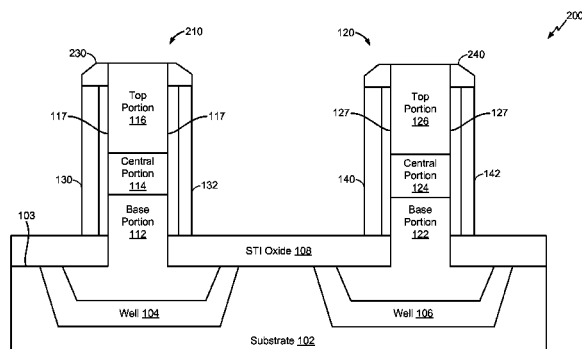
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(57)

ABSTRACT

A tunnel field transistor (TFET) device includes a fin structure that protrudes from a substrate surface. The fin structure includes a base portion proximate to the substrate surface, a top portion, and a first pair of sidewalls extending from the base portion to the top portion. The first pair of sidewalls has a length corresponding to a length of the fin structure. The fin structure also includes a first doped region having a first dopant concentration at the base portion of the fin structure. The fin structure also includes a second doped region having a second dopant concentration at the top portion of the fin structure. The TFET device further includes a gate including a first conductive structure neighboring a first sidewall of the first pair of sidewalls. A dielectric layer electrically isolates the first conductive structure from the first sidewall.

22 Claims, 12 Drawing Sheets



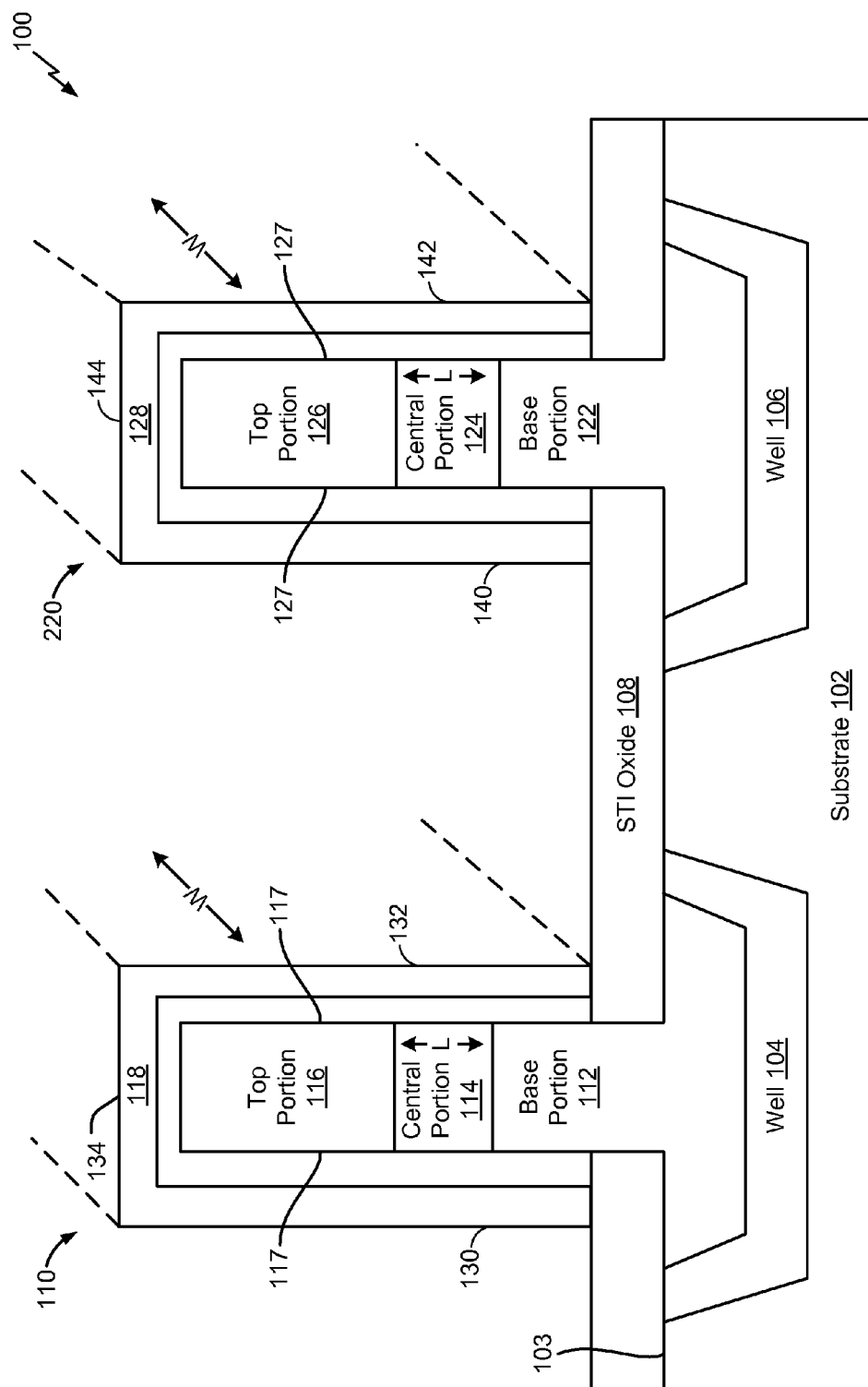


FIG. 1

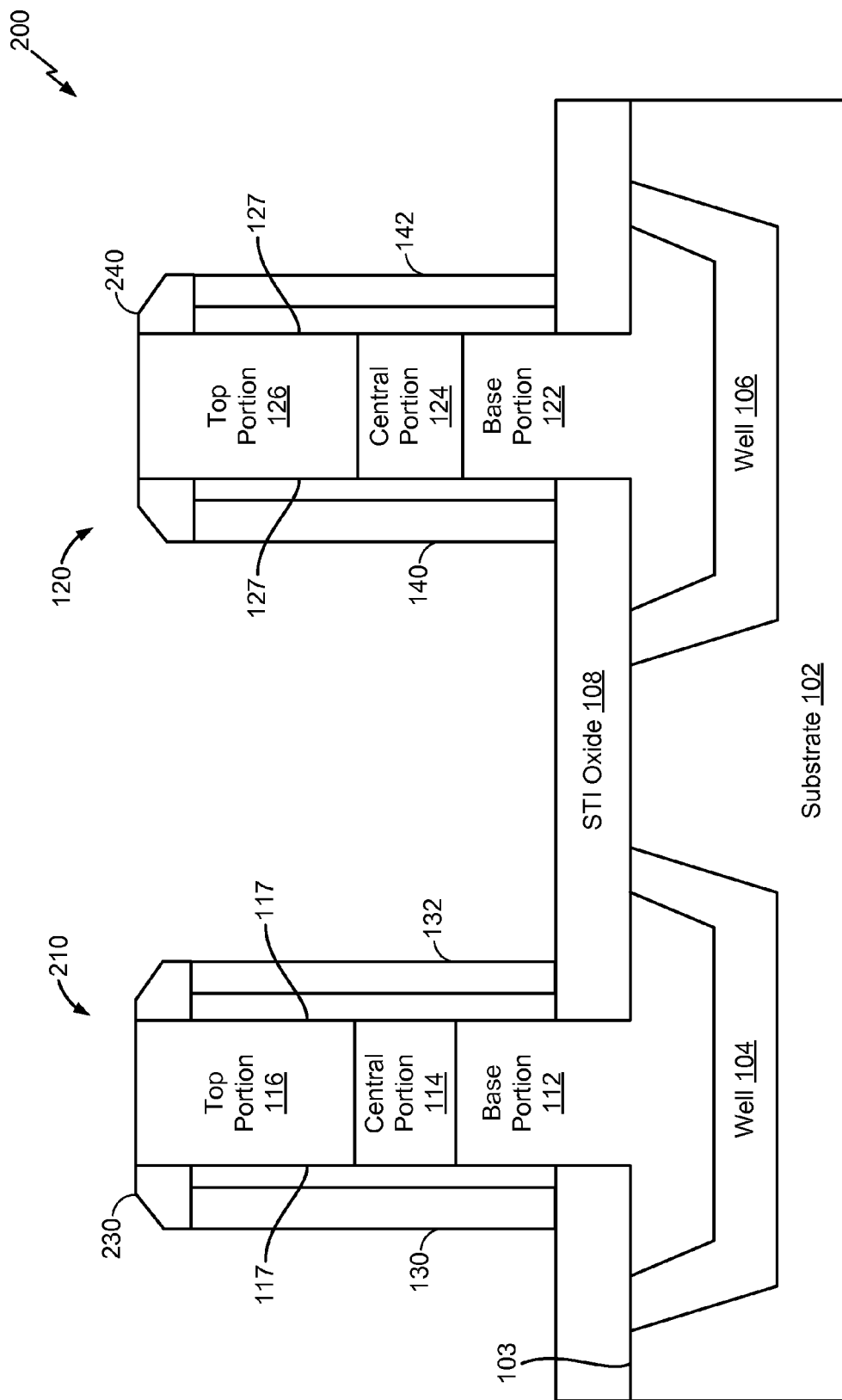


FIG. 2

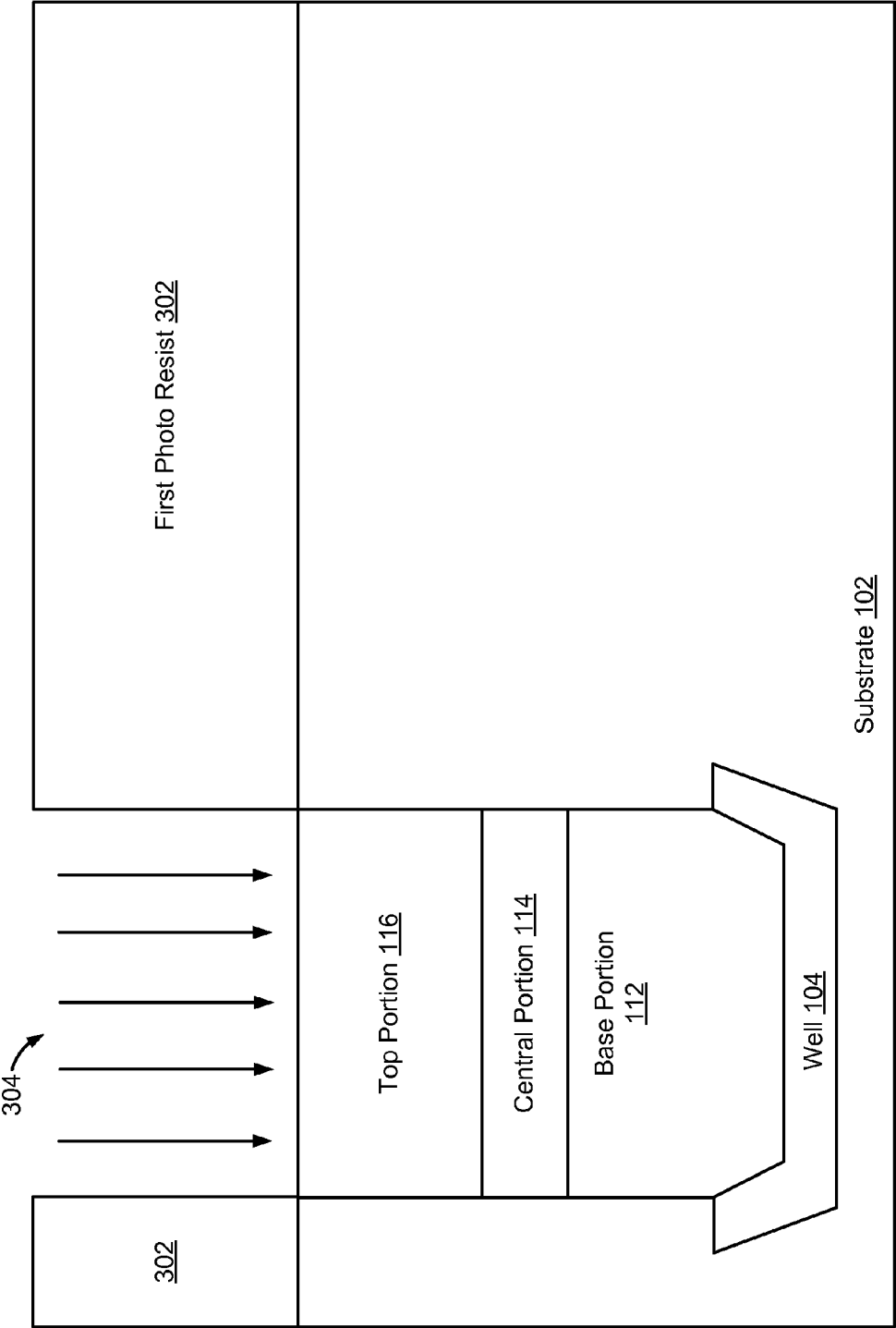


FIG. 3

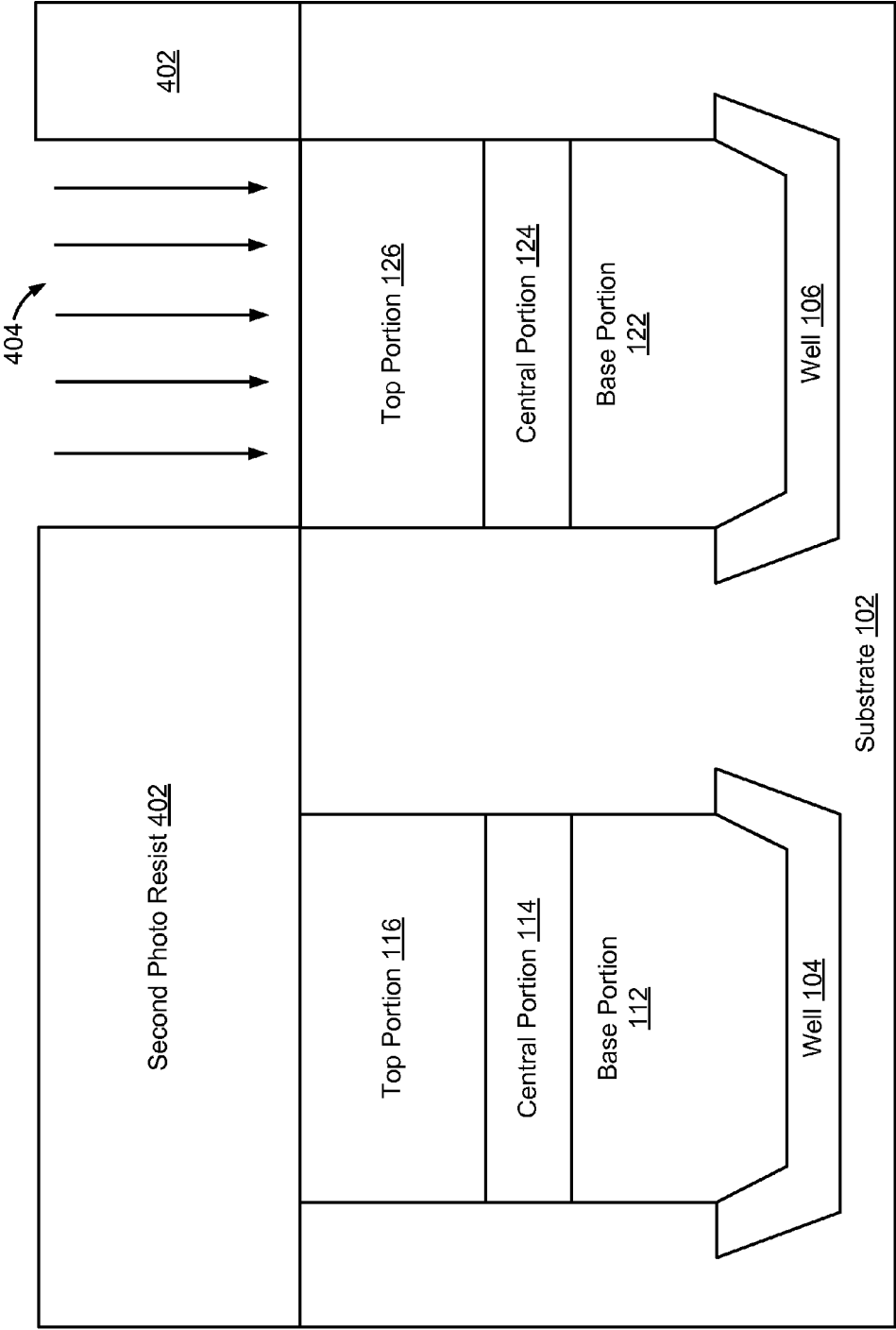


FIG. 4

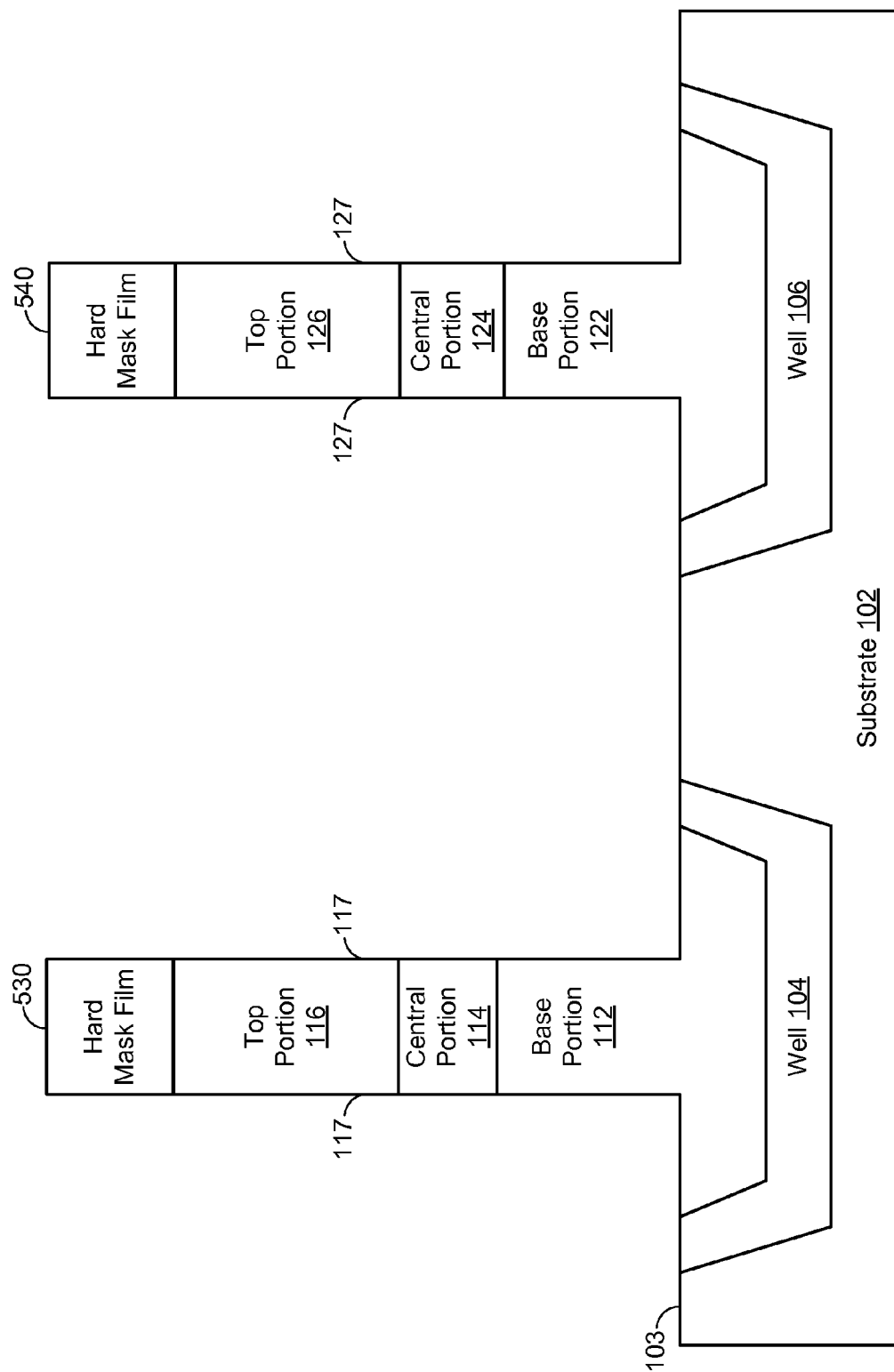


FIG. 5

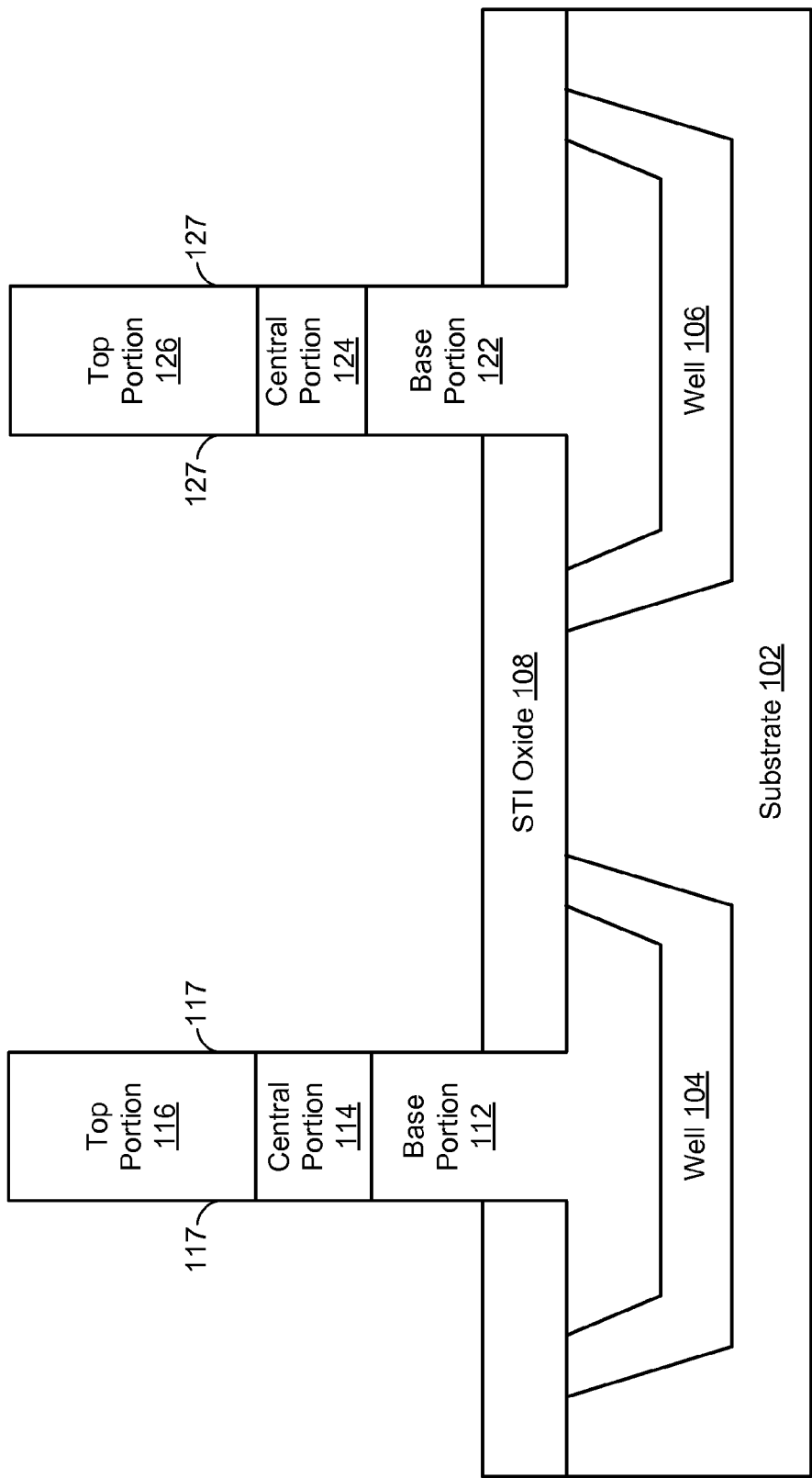


FIG. 6

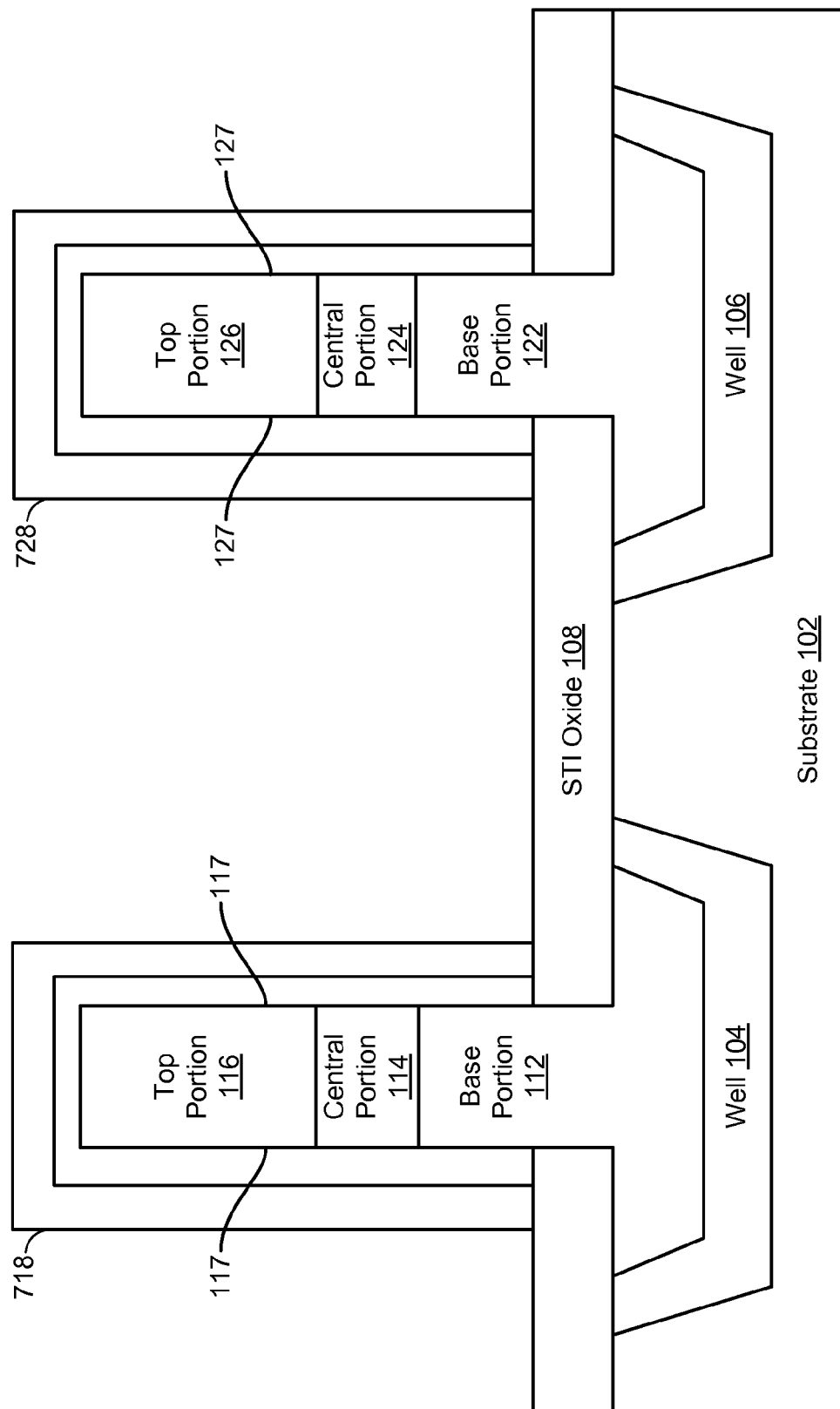


FIG. 7

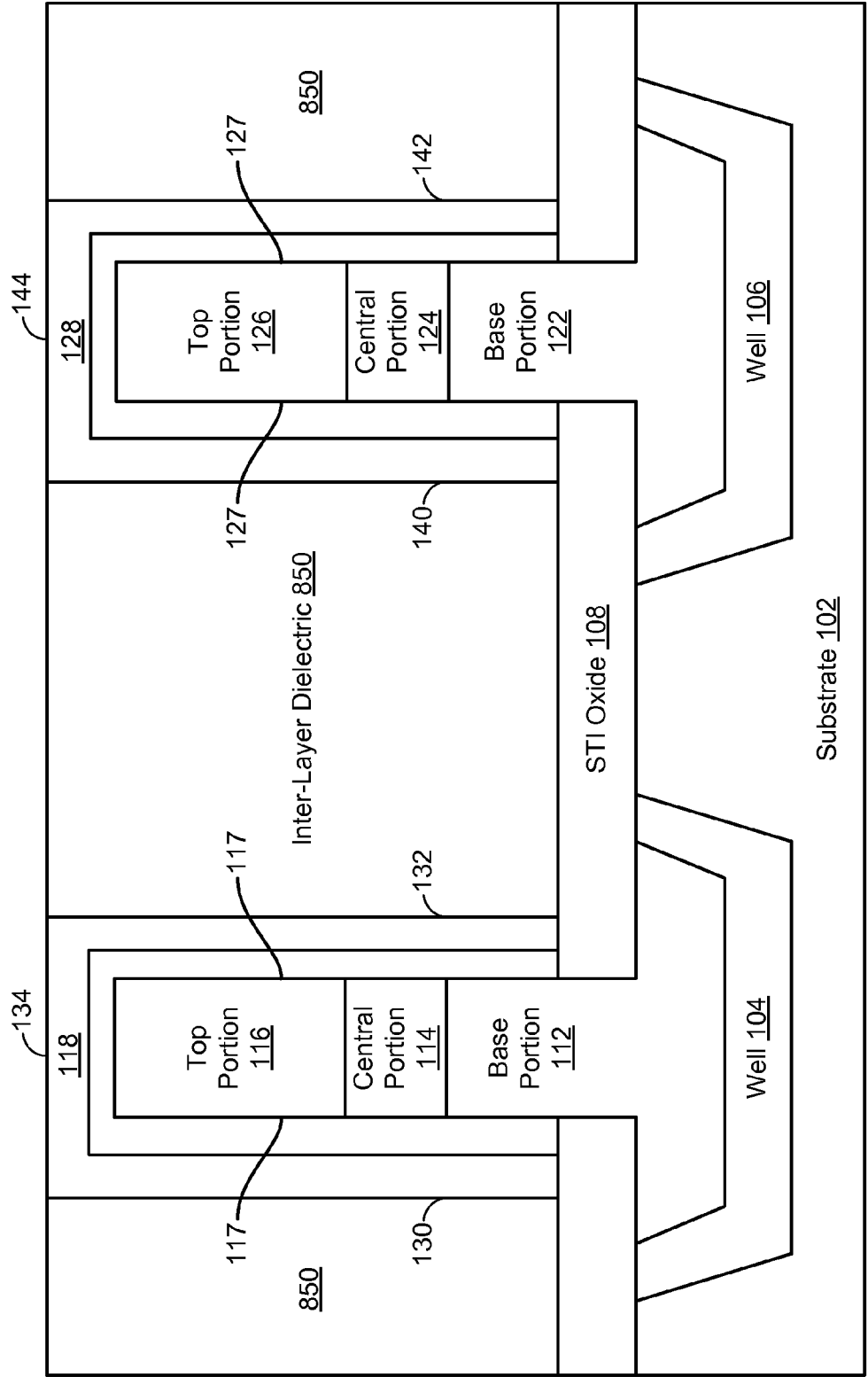


FIG. 8

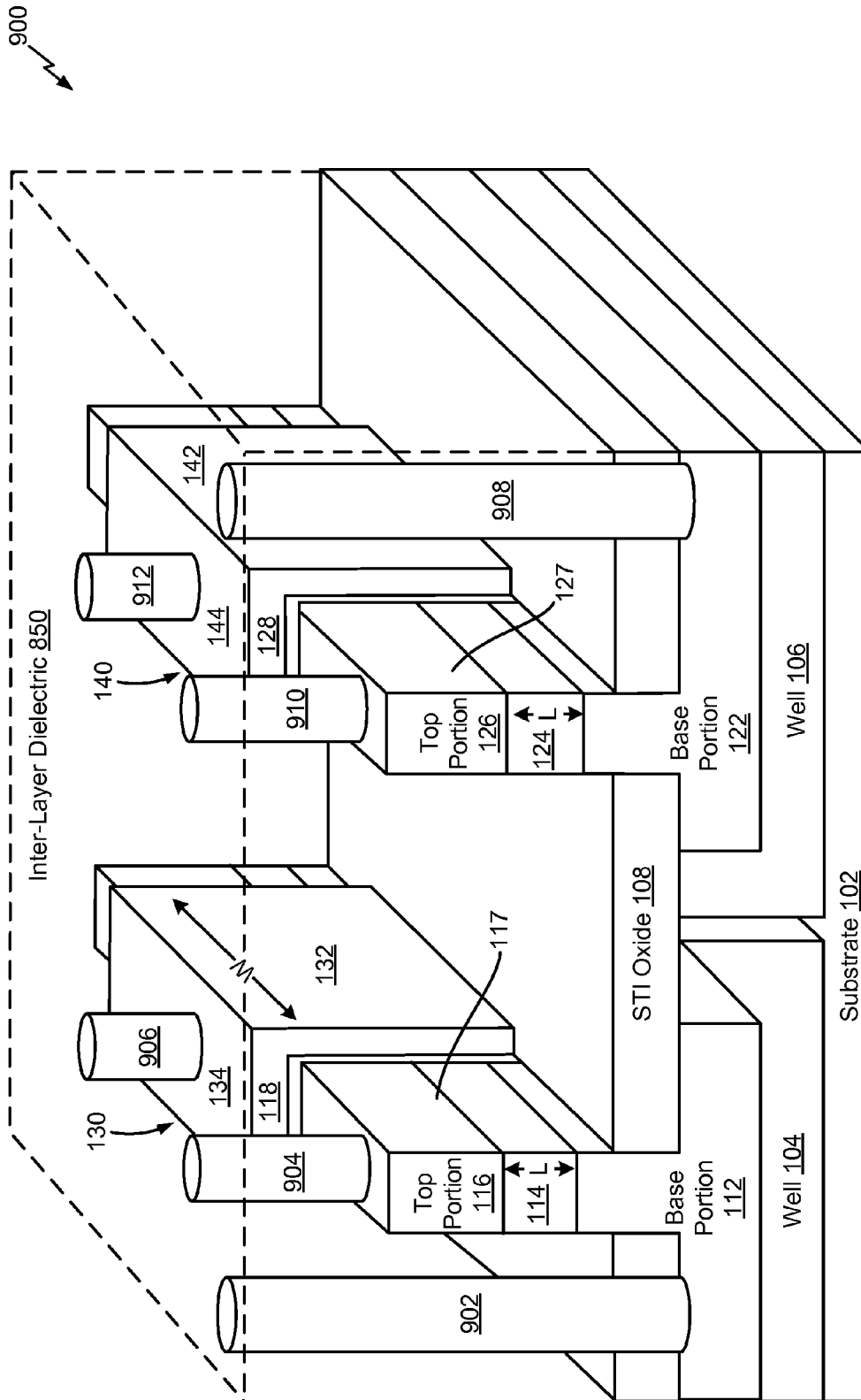
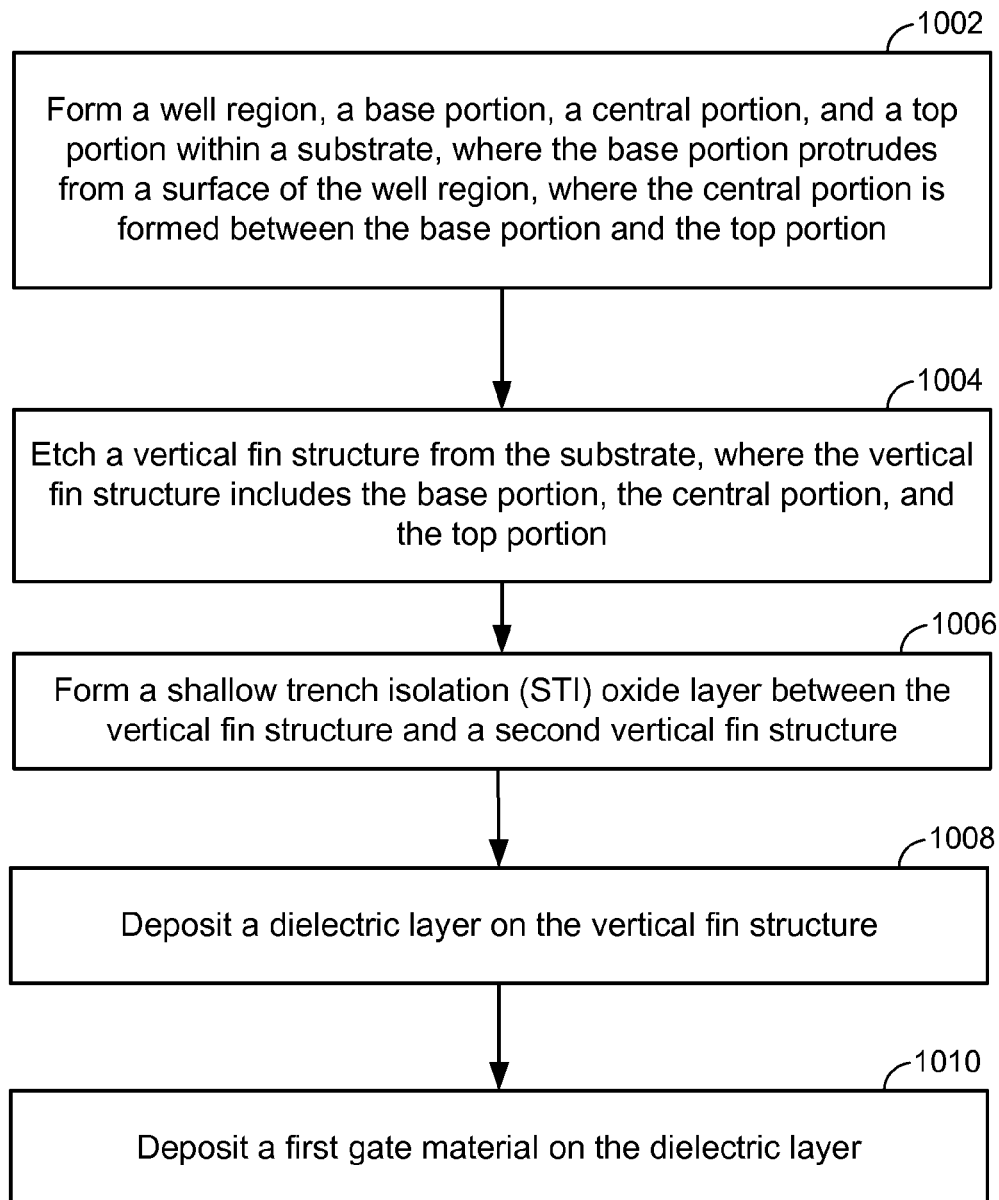


FIG. 9

**FIG. 10**

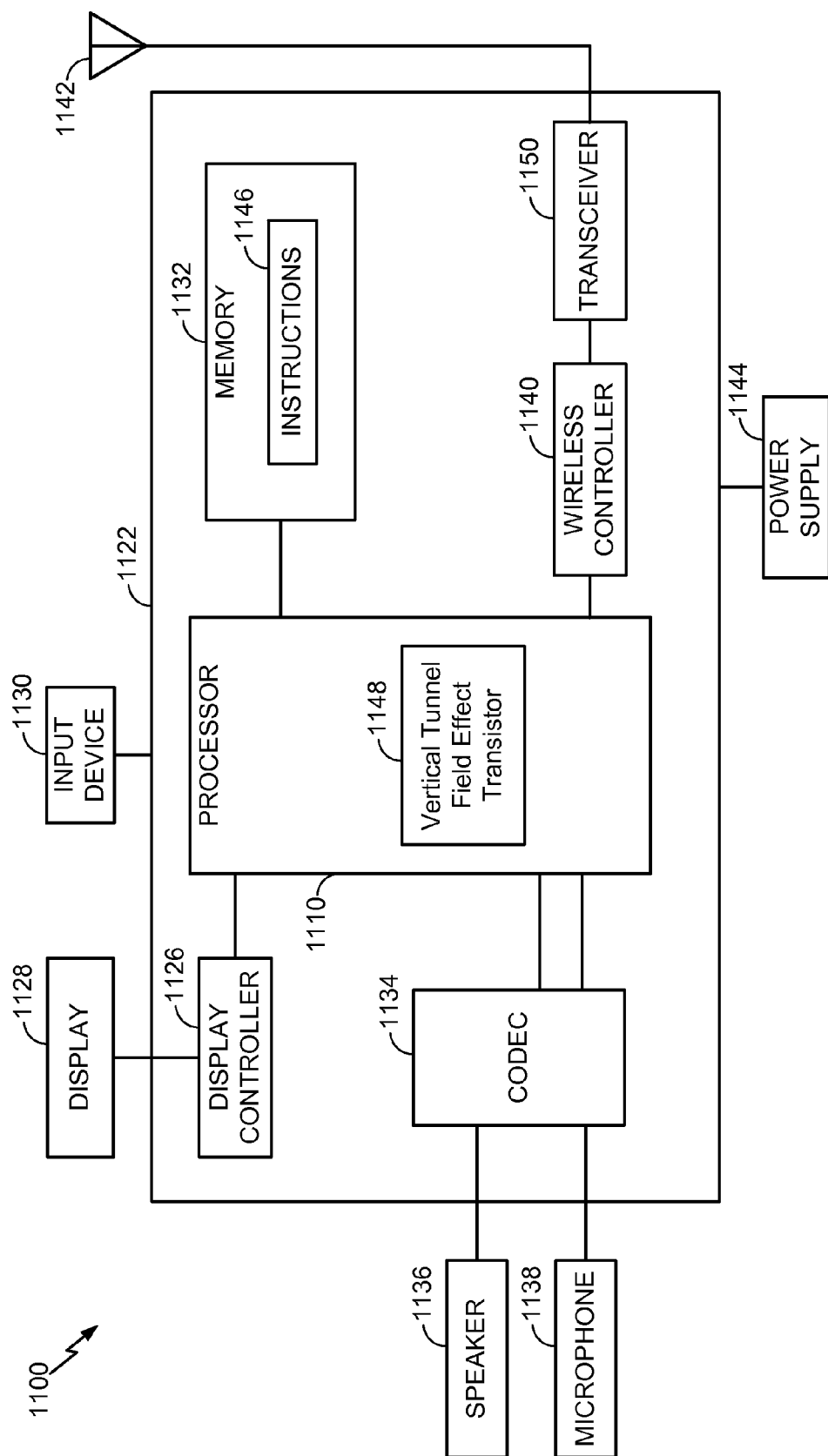


FIG. 11

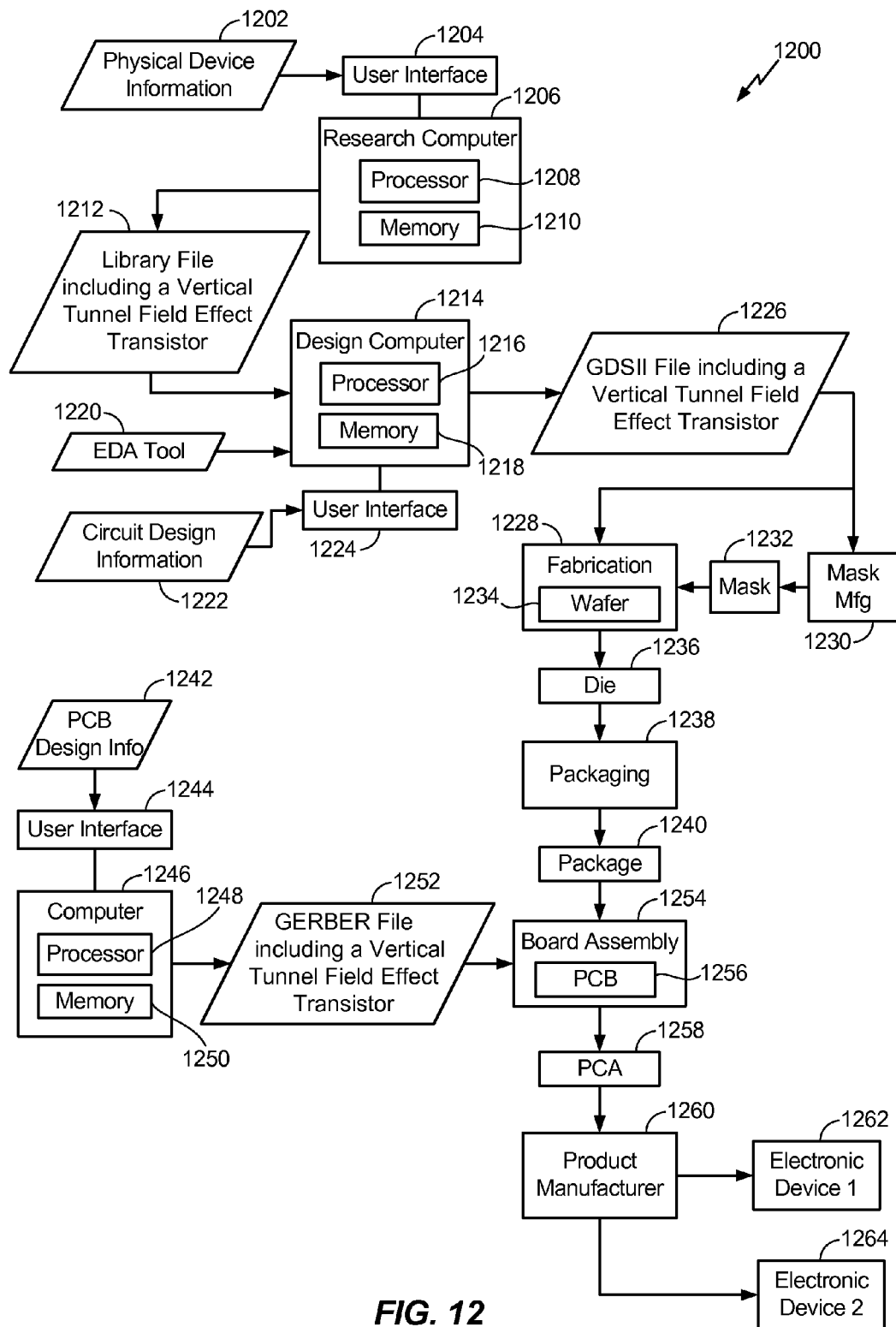


FIG. 12

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VERTICAL TUNNEL FIELD EFFECT TRANSISTOR

I. FIELD

The present disclosure is generally related to a vertical tunnel field effect transistor.

II. DESCRIPTION OF RELATED ART

Advances in technology have resulted in smaller and more powerful computing devices. For example, there currently exist a variety of portable personal computing devices, including wireless computing devices, such as portable wireless telephones, personal digital assistants (PDAs), and paging devices that are small, lightweight, and easily carried by users. More specifically, portable wireless telephones, such as cellular telephones and internet protocol (IP) telephones, may communicate voice and data packets over wireless networks. Further, many such wireless telephones include other types of devices that are incorporated therein. For example, a wireless telephone may also include a digital still camera, a digital video camera, a digital recorder, and an audio file player. Also, such wireless telephones may process executable instructions, including software applications, such as a web browser application, that may be used to access the Internet. As such, these wireless telephones may include significant computing capabilities.

A semiconductor device for use in wireless communication devices may include transistors (e.g., complementary metal-oxide-semiconductor (CMOS) transistors) that form logic circuits within the semiconductor device. Each CMOS transistor may include a gate, a source region, and a drain region. Upon activation, a gate bias of a traditional CMOS transistor may cause the formation of an accumulation region channel between the source region and the drain region to permit current flow from the source region to the drain region. In contrast, a tunnel CMOS transistor may enable current flow as a result of band-to-band tunneling in a channel enabled by an applied gate bias. However, because tunnel CMOS transistors are typically planar, such tunnel CMOS transistors may present scaling challenges for sub-22 nanometer (nm) process dimensions and beyond.

III. SUMMARY

A vertical tunnel field effect transistor (TFET) and a method of fabrication are disclosed. A fin-type vertical TFET may include a source region and a drain region that are vertically coupled via a channel region. A vertical tunnel may be formed within the channel region to create a conduction path between the source region and the drain region. The length of the vertical tunnel may be dependent on the height of the channel region. The fin-type vertical TFET may also include a gate with an adjustable width. For example, an amount of saturation current that flows through the vertical tunnel may be adjusted (e.g., increased or decreased) in response to changing the width of the gate.

In a particular embodiment, a tunnel field transistor (TFET) device includes a fin structure that protrudes from a substrate surface. The fin structure includes a base portion proximate to the substrate surface, a top portion, and a first pair of sidewalls extending from the base portion to the top portion. The first pair of sidewalls has a length corresponding to a length of the fin structure. The fin structure also includes a first doped region having a first dopant concentration at the base portion of the fin structure. The fin structure also

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includes a second doped region having a second dopant concentration at the top portion of the fin structure. The TFET device further includes a gate including a first conductive structure neighboring a first sidewall of the first pair of sidewalls. A dielectric layer electrically isolates the first conductive structure from the first sidewall.

In another particular embodiment, a method includes fabricating a vertical tunnel field effect transistor (TFET) device. Fabricating the vertical TFET device includes forming a well region, a base portion, a central portion, and a top portion within a substrate. The base portion protrudes from a surface of the well region, and the central portion is formed between the base portion and the top portion. Fabricating the vertical TFET device also includes etching the substrate to form a vertical fin structure. The vertical fin structure includes the base portion, the central portion, and the top portion. Fabricating the vertical TFET device further includes depositing a dielectric layer on the vertical fin structure and depositing a first gate material on the dielectric layer.

In another particular embodiment, an apparatus includes means for providing charge carriers to a tunneling channel and means for receiving the charge carriers from the tunneling channel. One of the means for providing or the means for receiving is at a base portion of a fin structure and is adjacent to a substrate surface. The other of the means for providing or the means for receiving is at a top portion of the fin structure. The apparatus also includes means for biasing the tunneling channel to enable band-to-band tunneling at the tunneling channel.

One particular advantage provided by at least one of the disclosed embodiments is an ability to form band-to-band tunneling currents in channels of tunnel field effect transistors for sub-22 nanometer (nm) process dimensions and beyond. Other aspects, advantages, and features of the present disclosure will become apparent after review of the entire application, including the following sections: Brief Description of the Drawings, Detailed Description, and the Claims.

IV. BRIEF DESCRIPTION OF THE DRAWINGS

FIG. 1 is a diagram of a particular illustrative embodiment of a vertical tunnel field effect transistor device;

FIG. 2 is a diagram of another particular illustrative embodiment of a vertical tunnel field effect transistor device;

FIG. 3 is a diagram illustrating a particular stage of fabricating the vertical tunnel field effect transistor device of FIG. 1;

FIG. 4 is a diagram illustrating another stage of fabricating the vertical tunnel field effect transistor device of FIG. 1;

FIG. 5 is a diagram illustrating another particular stage of fabricating the vertical tunnel field effect transistor device of FIG. 1;

FIG. 6 is a diagram illustrating another stage of fabricating the vertical tunnel field effect transistor device of FIG. 1;

FIG. 7 is a diagram illustrating another particular stage of fabricating the vertical tunnel field effect transistor device of FIG. 1;

FIG. 8 is a diagram illustrating another particular stage of fabricating the vertical tunnel field effect transistor device of FIG. 1;

FIG. 9 is a diagram of a particular illustrative embodiment of a three-dimensional vertical tunnel field effect transistor device;

FIG. 10 is a flowchart of a particular illustrative embodiment of a method of fabricating a vertical tunnel field effect transistor device;

FIG. 11 is a block diagram of a wireless communication device including a vertical tunnel field effect transistor device; and

FIG. 12 is a data flow diagram of a particular illustrative embodiment of a process to manufacture electronic devices that include a vertical tunnel field effect transistor device.

V. DETAILED DESCRIPTION

Particular embodiments of vertical tunnel field effect transistor devices and methods of fabrication are presented in this disclosure. It should be appreciated, however, that the concepts and insights applied to the particular embodiments with respect to designs of the vertical tunnel field effect transistor devices and with respect to how to make the vertical tunnel field effect transistor devices may be embodied in a variety of contexts. The particular embodiments presented are merely illustrative of specific ways to design and make the vertical tunnel field effect transistor devices and do not limit the scope of this disclosure.

The present disclosure describes the particular embodiments in specific contexts. However, features, methods, structures or characteristics described according to the particular embodiments may also be combined in suitable manners to form one or more other embodiments. In addition, figures are used to illustrate the relative relationships between the features, methods, structures, or characteristics, and thus may not be drawn in scale. Directional terminology, such as “top,” “central,” “base,” etc. is used with reference to the orientation of the figures being described. The components of the disclosure may be positioned in a number of different orientations. As such, the directional terminology is used for purposes of illustration and is not meant to be limiting.

Referring to FIG. 1, a particular illustrative embodiment of a fin-type vertical tunnel field effect transistor (TFET) device 100 is shown. FIG. 1 shows a cross-sectional view of a portion of the vertical TFET device 100.

The vertical TFET device 100 includes a substrate 102 and a shallow trench isolation (STI) oxide layer 108. The substrate 102 may be a p-type substrate. In a particular embodiment, the substrate 102 is a silicon (Si) substrate. The STI oxide layer 108 may prevent electrical current leakage between adjacent semiconductor device components. For example, the STI oxide layer 108 may prevent electrical current leakage between the vertical TFET device 100 and another semiconductor device component (e.g., another vertical TFET device).

The vertical TFET device 100 includes a first vertical TFET 110 that includes a first well region 104, a first base portion 112, a first central portion 114, and a first top portion 116. In a particular embodiment, the first base portion 112, the first central portion 114, and the first top portion 116 are made of a same type of material. For example, the first base portion 112, the first central portion 114, and the first top portion 116 may be made of silicon (Si). In another particular embodiment, the portions 112-116 may be made of at least one III-V material. For example, the portions 112-116 may be made of aluminum arsenide, gallium arsenide, gallium nitride, gallium phosphide, indium antimonide, indium arsenide, indium phosphide, or any combination thereof. In another particular embodiment, the portions 112-116 may be made of at least one II-VI material. The first base portion 112 may be adjacent to (e.g., proximate to) the surface 103 of the substrate 102. The first base portion 112 may correspond to a first doped region having a first dopant concentration, and the first top portion 116 may correspond to a second doped region having a second dopant concentration. The first vertical TFET

110 may also include a first pair of sidewalls 117 extending from the first base portion 112 to the first top portion 116. A first dielectric layer (e.g., a material having a high dielectric constant (k)) may be deposited around the sidewalls 117.

The first base portion 112, the first central portion 114, the first top portion 116, and the first pair of sidewalls 117 correspond to a first fin structure. The first central portion 114 may correspond to a channel region of the first fin structure, and a channel length (L) may correspond to a height of the first central portion 114. In a particular embodiment, the first top portion 116 may correspond to a drain of the first fin structure and the first base portion 112 may correspond to a source of the first fin structure. In another particular embodiment, the first top portion 116 may correspond to a source of the first fin structure and the first base portion 112 may correspond to a drain of the first fin structure. The first fin structure may protrude from the surface 103 of the substrate 102. The first vertical TFET 110 may also include a first gate 118 that includes a first conductive structure 130 that is adjacent to (e.g., neighboring) at least one sidewall of the first pair of sidewalls 117. The first gate 118 may also include a second conductive structure 132 that is adjacent to (e.g., neighboring) at least one other sidewall of the first pair of sidewalls 117 and a third conductive structure 134 that is adjacent to (e.g., neighboring) the first top portion 116. The third conductive structure 134 may be coupled to the first conductive structure 130 and to the second conductive structure 132. A width (w) of the first gate 118 may be changed to adjust a saturation current of the first vertical TFET 110. The first dielectric layer may electrically isolate the conductive structures 130-134 (e.g., the first gate 118) from the sidewalls 117 and from the first top portion 116, respectively.

The vertical TFET device 100 also includes a second vertical TFET 120 that includes a second well region 106, a second base portion 122, a second central portion 124, and a second top portion 126. In a particular embodiment, the second base portion 122, the second central portion 124, and the second top portion 126 are made of a same type of material. For example, the second base portion 122, the second central portion 124, and the second top portion 126 may be made of silicon (Si). The second base portion 122 may also be adjacent to (e.g., proximate to) the surface 103 of the substrate 102. The second base portion 122 may correspond to a third doped region having a third dopant concentration, and the second top portion 126 may correspond to a fourth doped region having a fourth dopant concentration. The second vertical TFET 120 may also include a second pair of sidewalls 127 extending from the second base portion 122 to the second top portion 126. A second dielectric layer (e.g., a material having a high dielectric constant (k)) may be deposited around the sidewalls 127.

The second base portion 122, the second central portion 124, the second top portion 126, and the second pair of sidewalls 127 correspond to a second fin structure. The second central portion 124 may correspond to a channel of the second fin structure, and a channel length (L) may correspond to a height of the second central portion 124. The channel length (L) of the first central portion 114 may be equal to (or substantially equal to) the channel length (L) of the second central portion 124. Alternatively, the first central portion 114 and the second central portion 124 may have different channel lengths (L).

In a particular embodiment, the second top portion 126 may correspond to a drain of the second fin structure and the second base portion 122 may correspond to a source of the second fin structure. In another particular embodiment, the second top portion 126 may correspond to a source of the

second fin structure and the second base portion **122** may correspond to a drain of the second fin structure. The second fin structure protrudes from the surface **103** of the substrate **102**. The second vertical TFET **120** may also include a second gate **128** that includes a first conductive structure **140** that is adjacent to (e.g., neighboring) at least one sidewall of the second pair of sidewalls **127**. The second gate **128** may also include a second conductive structure **142** that is adjacent to (e.g., neighboring) at least one other sidewall of the second pair of sidewalls **127** and a third conductive structure **144** that is adjacent to (e.g., neighboring) the second top portion **126**. The third conductive structure **144** may be coupled to the first conductive structure **140** and to the second conductive structure **142**. As further illustrated in FIG. 9, a width of the second gate **128** may be changed to adjust a saturation current of the second vertical TFET **120**. The second dielectric layer may electrically isolate the conductive structures **140-144** (e.g., the second gate **128**) from the sidewalls **127** and from the second top portion **126**, respectively.

In a particular embodiment, the first vertical TFET **110** and the second vertical TFET **120** are complementary TFETs. For example, the first vertical TFET **110** may be an n-type TFET and the second vertical TFET **120** may be a p-type TFET. Alternatively, the first vertical TFET **110** may be a p-type TFET and the second vertical TFET **120** may be an n-type TFET.

Three particular embodiments of the vertical TFET device **100** are described below. In each embodiment, the first vertical TFET **110** is an n-type TFET and the second vertical TFET **120** is a p-type TFET. For example, the first gate **118** may be comprised of a metal having an n-type work function and the second gate **128** may be comprised of a metal having a p-type work function. These embodiments are described for purposes of illustration and are not meant to be limiting. For example, in other embodiments, the first vertical TFET **110** may be an n-type TFET and the second vertical TFET **120** may be a p-type TFET, each vertical TFET **110, 120** may be a p-type TFET, or each vertical TFET **110, 120** may be an n-type TFET.

In a first particular embodiment, the first well region **104** and the second well region **106** may be doped with an n-type concentration. The first base portion **112** (e.g., the first doped region) may correspond to a source of the first fin structure having a first dopant concentration that includes a P+ concentration. For example, a p+ type silicon may be placed (e.g., implanted) in the substrate **102** and at the bottom of the first fin structure as a source. The first central portion **114** may have a dopant concentration that includes a P- concentration. For example, a p- type silicon may be placed (e.g., implanted) between the first top portion **116** and the first base portion **112** as a channel region. The first top portion **116** (e.g., the second doped region) may correspond to a drain of the first fin structure having a second dopant concentration that includes an N+ concentration. For example, an n+ type silicon may be placed (e.g., implanted) at the top of the first fin structure as a drain. In the first particular embodiment, the second base portion **122** (e.g., the third doped region) may correspond to a drain of the second fin structure having a third dopant concentration that includes a P+ concentration, the second central portion **124** may have a dopant concentration that includes an N- concentration, and the second top portion **126** (e.g., the fourth doped region) may correspond to a source of the second fin structure having a fourth dopant concentration that includes an N+ concentration.

As variance of a first particular embodiment, the first top portion **116** of the first vertical TFET **110** and the second top portion **126** of the second vertical TFET **120** can be com-

prised of different materials than the central portions **114, 124** and the base portions **112, 122**. For example, the top portions **116, 126** can be an n-type metal, an n-type polysilicon, etc.

In a second particular embodiment, the first well region **104** and the second well region **106** may be doped with a p-type concentration. The first base portion **112** (e.g., the first doped region) may correspond to a drain of the first fin structure having a first dopant concentration that includes an N+ concentration. For example, an n+ type silicon may be placed in the substrate **102** and at the bottom of the first fin structure as a drain. The first central portion **114** may have a dopant concentration that includes a P- concentration. For example, a p- type silicon may be placed between the first top portion **116** and the first base portion **112** as a channel region. The first top portion **116** (e.g., the second doped region) may correspond to a source of the first fin structure having a second dopant concentration that includes a P+ concentration. For example, a p+ type silicon may be placed at the top of the first fin structure as a source. In the second particular embodiment, the second base portion **122** (e.g., the third doped region) may correspond to a source of the second fin structure having a third dopant concentration that includes an N+ concentration, the second central portion **124** may have a dopant concentration that includes an N- concentration, and the second top portion **126** (e.g., the fourth doped region) may correspond to a drain of the second fin structure having a fourth dopant concentration that includes a P+ concentration.

As variance of a second particular embodiment, the first top portion **116** of the first vertical TFET **110** and the second top portion **126** of the second vertical TFET **120** can be comprised of different materials than the central portions **114, 124** and the base portions **112, 122**. For example, the top portions **116, 126** can be a p-type metal, a p-type polysilicon, etc.

In a third particular embodiment, the first well region **104** may be doped with an n-type concentration and the second well region **106** may be doped with a p-type concentration. The first base portion **112** (e.g., the first doped region) may correspond to a source of the first fin structure having a first dopant concentration that includes a P+ concentration. For example, a p+ type silicon may be placed in the substrate **102** and at the bottom of the first fin structure as a source. The first central portion **114** may have a dopant concentration that includes a P- concentration. For example, a p- type silicon may be placed between the first top portion **116** and the first base portion **112** as a channel region. The first top portion **116** (e.g., the second doped region) may correspond to a drain of the first fin structure having a second dopant concentration that includes an N+ concentration. For example, an n+ type silicon may be placed at the top of the first fin structure as a drain. In the third particular embodiment, the second base portion **122** (e.g., the third doped region) may correspond to a source of the second fin structure having a third dopant concentration that includes an N+ concentration, the second central portion **124** may have a dopant concentration that includes an N- concentration, the second top portion **126** (e.g., the fourth doped region) may correspond to a drain of the second fin structure having a fourth dopant concentration that includes a P+ concentration.

As variance of the third particular embodiment, the first top portion **116** of the first vertical TFET **110** and the second top portion **126** of the second vertical TFET **120** can be comprised of different materials than the central portions **114, 124** and the base portions **112, 122**. For example, the first top portion **116** can be an n-type metal or an n-type polysilicon, and the second top portion **126** can be a p-type metal or a p-type polysilicon, etc.

A first contact may be coupled to the first base portion **112**, a second contact may be coupled to the first top portion **116**, and a third contact may be coupled to the first gate **118**, as further described with respect to FIG. 9. Voltages applied to each portion **112**, **116**, **118** via the contacts may cause a first vertical tunneling current to flow between the first top portion **116** and the first base portion **112** via a channel in the first central portion **114**. A channel length (L) may be defined by the height of the first central portion **114**. For example, the length (L) of the channel may correspond to a thickness of a channel film in an embodiment where the first central portion **114** is grown or deposited on the first base portion **112**. Similarly, a fourth contact may be coupled to the second base portion **122**, a fifth contact may be coupled to the second top portion **126**, and a sixth contact may be coupled to the second gate **128**. Voltages applied to the each portion **122**, **126**, **128** via the contacts may cause a second vertical tunneling current to flow between the second top portion **126** and the second base portion **122** via a channel in the second central portion **124**. A channel length (L) may be defined by the height of the second central portion **124**.

It will be appreciated that the first central portion **114** and the second central portion **124** may permit the formation of band-to-band tunneling currents in channels, where the lengths (L) of the channels are independent of the width of the gates **118**, **128**. The gates **118**, **128** may be independently designed and/or adjusted to manage an amount of saturation current supported by the vertical TFETs **110**, **120** without affecting the length (L) of the channels. The height of the central portions **114**, **124** (e.g., the channel lengths) may also be designed independently of a lithography process used for designing the gates. For example, because the channel is vertical (as opposed to planar), the channel is not limited to a region or a location that is under a planar gate of a field effect transistor.

Referring to FIG. 2, another particular illustrative embodiment of a fin-type vertical tunnel field effect transistor device **200** is shown. FIG. 2 shows a cross-sectional view of a portion of the vertical TFET device **200**.

The vertical TFET device **200** may include a first vertical TFET **210** and a second vertical TFET **220**. The first vertical TFET **210** and the second vertical TFET **220** may correspond to the first vertical TFET **110** of FIG. 1 and the second vertical TFET **120** of FIG. 1, respectively, and may operate in a substantially similar manner. For example, the first vertical TFET **210** may include the first base portion **112**, the first central portion **114**, the first top portion **116**, the first pair of sidewalls **117**, the first conductive structure **130**, and the second conductive structure **132**. The second vertical TFET **220** may include the second base portion **122**, the second central portion **124**, the second top portion **126**, the second pair of sidewalls **127**, the first conductive structure **140**, and the second conductive structure **142**.

The first vertical TFET **210** may include a first hard mask film **230** that is deposited on the first gate **118** and on the first pair of sidewalls **117**. The second vertical TFET **220** may include a second hard mask film **240** that is deposited on the second gate **128** and on the second pair of sidewalls **127**. The hard mask films **230**, **240** may be deposited during fabrication as described with respect to FIG. 5.

It will be appreciated that the first top portion **116** and the second top portion **126** of the vertical TFETs **210**, **220**, respectively, are not covered by a gate material. As a result, contacts may be vertically coupled to the first top portion **116** and to the second top portion **126** from above the fin-type vertical tunnel field effect transistor device **200**. Vertically coupling the contacts to the first top portion **116** and to the

second top portion **126** may reduce series parasitic resistance in the vertical TFETs **210**, **220**.

For ease of illustration, the following description corresponds to fabrication stages for the first particular embodiment of the vertical TFET device **100** described with respect to FIG. 1. However, the fabrication stages may be modified to fabricate the second embodiment, the third embodiment, or any other embodiments.

Referring to FIG. 3, a particular stage of fabricating the vertical tunnel field effect transistor device of FIG. 1 is shown. During the particular stage shown in FIG. 3, a first photoresist **302** may be patterned on top of the substrate **102**. For example, the first photoresist **302** may be patterned to select (e.g., expose) a particular area of the substrate **102** to implant the first vertical TFET **110**. After patterning the first photoresist **302**, the first vertical TFET **110** may be implanted.

Implanting the first vertical TFET **110** may include implanting the first well region **104** in the substrate **102** using ion implantation **304**. For example, n-type implantation may be performed in the substrate **102** to create the first well region **104**. After the first well region **104** is implanted in the substrate **102**, the first base portion **112** may be implanted in the first well region **104** using ion implantation **304**. For example, P+ implantation may be performed in the first well region **104** to create the first base portion **112**. After the first base portion **112** is implanted in the first well region **104**, the first central portion **114** may be implanted on top of the first base portion **112** using ion implantation **304**. For example, P- implantation may be performed in the substrate **102** and on top of the first base portion **112** to create the first central portion **114**. After the first central portion **114** is implanted on the first base portion **112**, the first top portion **116** may be implanted on top of the first central portion **114** using ion implantation **304**. For example, N+ implantation may be performed in the substrate **102** and on top of the first central portion **114** to create the first top portion **116**.

After the first vertical TFET **110** is implanted, the first photoresist **302** may be removed. For example, the first photoresist **302** may be removed via photoresist stripping to prevent the substrate **102** and the first vertical TFET **110** from being subjected to chemicals used during removal. In a particular embodiment, the first photoresist may be removed via organic photoresist stripping, inorganic photoresist stripping, or dry photoresist stripping.

FIG. 3 illustrates implantation of the first vertical TFET **110** and FIG. 4 illustrates implantation of the second vertical TFET **120**. During the particular stage shown in FIG. 4, a second photoresist **402** may be patterned on top of the substrate **102** and the first vertical TFET **110**. For example, the second photoresist **402** may be patterned to select (e.g., expose) a particular area of the substrate **102** to implant the second vertical TFET **120**. After patterning the second photoresist **402**, the second vertical TFET **120** may be implanted.

Implanting the second vertical TFET **120** may include implanting the second well region **106** in the substrate **102** using ion implantation **404**. For example, n-type implantation may be performed in the substrate **102** to create the second well region **106**. After the second well region **106** is implanted in the substrate **102**, the second base portion **122** may be implanted in the second well region **106** using ion implantation **404**. For example, P+ implantation may be performed in the second well region **106** to create the second base portion **122**. After the second base portion **122** is implanted in the second well region **106**, the second central portion **124** may be implanted on top of the second base portion **122** using ion implantation **404**. For example, P- implantation may be per-

formed in the substrate **102** and on top of the second base portion **122** to create the second central portion **124**. After the second central portion **124** is implanted on the second base portion **122**, the second top portion **126** may be implanted on top of the second central portion **124** using ion implantation **404**. For example, N+ implantation may be performed in the substrate **102** and on top of the second central portion **124** to create the second top portion **126**.

After the second vertical TFET **120** is implanted, the second photoresist **402** may be removed. For example, the second photoresist **402** may be removed via photoresist stripping to prevent the substrate **102**, the first vertical TFET **110**, the second vertical TFET **120**, or any combination thereof, from being subjected to chemicals used during removal.

Referring to FIG. 5, another particular stage of fabricating the vertical tunnel field effect transistor device of FIG. 1 is shown. During the particular stage shown in FIG. 5, a first hard mask film **530** may be patterned on the first vertical TFET **110** and a second hard mask film **540** may be patterned on the second vertical TFET **120**. For example, the first hard mask film **530** may be deposited on top of the first top portion **116** and the substrate **102**. The second hard mask film **540** may be deposited on top of the second top portion **126** and the substrate **102**. In a particular embodiment, the first hard mask film **530** and the second hard mask film **540** may be a single hard mask film deposited across the top of the vertical TFET device illustrated in FIG. 4 after the second photoresist **402** is removed.

The hard mask films **530**, **540** may be patterned on top of the first top portion **116** and the second top portion **126**, respectively, to protect areas beneath the hard mask films **530**, **540** during etching. After patterning the hard mask films **530**, **540**, the first fin structure and the second fin structure may be etched from the substrate **102**. For example, areas of the substrate **102** that are not protected by the hard mask films **530**, **540** may be etched down to the well regions **104**, **106**.

Referring to FIG. 6, another particular stage of fabricating the vertical tunnel field effect transistor device of FIG. 1 is shown. During the particular stage shown in FIG. 6, the STI oxide layer **108** is deposited. For example, the STI oxide layer **108** may be deposited on the substrate **102**, the well regions **104**, **106**, and the particular areas of the base portions **112**, **122** that are not protected by the hard mask films **530**, **540**. The STI oxide layer **108** may be polished (e.g., via a chemical and mechanical polishing (CMP) process) and recess etched. After the STI oxide layer **108** is etched, the hard mask films **530**, **540** may be removed.

Referring to FIG. 7, another particular stage of fabricating the vertical tunnel field effect transistor device of FIG. 1 is shown. During the particular stage, the material having a high dielectric constant (k) may be deposited on the first fin structure. In addition, the material having a high dielectric constant (k) may be deposited on the second fin structure in a similar fashion. A first gate material **718** (e.g., poly-silicon) may be deposited and patterned around the first fin structure and a second gate material **728** (e.g., poly silicon) may be deposited and patterned around the second fin structure.

It will be appreciated that implanting and/or patterning a lightly doped drain (LDD) area may be bypassed by fabricating the vertical tunnel field effect transistor device. Fabricating the vertical tunnel field effect transistor may also relax a requirement for patterning the bottom of the base portions **112**, **122** (e.g., source and/or drain regions).

Referring to FIG. 8, another particular stage of fabricating the vertical tunnel field effect transistor device of FIG. 1 is shown. During the particular stage, an inter-layer dielectric oxide **850** is deposited. After depositing the inter-layer dielec-

tric oxide **850**, a CMP process is performed on the inter-layer dielectric oxide **850** to smooth the surface of the inter-layer dielectric oxide **850**. The first gate material **718** may be removed and an n-type metal gate may be deposited to create the first gate **118**. The second gate material **728** may also be removed and a p-type metal gate may be deposited to create the second gate **128**.

As a result, the first central portion **114** and the second central portion **124** may permit the formation of band-to-band tunneling currents in channels, where the lengths (L) of the channels are independent of the width of the gates **118**, **128**. The gates **118**, **128** may be independently designed and/or adjusted to manage an amount of saturation current supported by the vertical TFETs **110**, **120** without affecting the length (L) of the channels. The height of the central portions **114**, **124** (e.g., the channel lengths) may also be designed independently of a lithography process used for designing the gates. For example, because the channel is vertical (as opposed to planar), the channel is not limited to a region or a location that is under a planar gate of a field effect transistor.

Referring to FIG. 9, a particular illustrative embodiment of a three-dimensional vertical tunnel field effect transistor device **900** is shown. The three-dimensional vertical TFET device **900** may correspond to the vertical TFET device **100** of FIG. 1.

The vertical TFET device **900** may include a first contact **902** coupled to the first base portion **112**, a second contact **904** coupled to the first top portion **116**, and a third contact **906** coupled to the first gate **118**. Voltages applied to each portion **112**, **116**, **118** via the respective contacts **902-906** may cause the first vertical tunneling current to flow between the first top portion **116** and the first base portion **112** via a channel in the first central portion **114**, as described with respect to FIG. 1. The vertical TFET device **900** may also include a fourth contact **908** coupled to the second base portion **122**, a fifth contact **910** coupled to the second top portion **126**, and a sixth contact **912** coupled to the second gate **128**. Voltages applied to each portion **122**, **126**, **128** via the respective contacts **908-912** may cause the second vertical tunneling current to flow between the second top portion **126** and the second base portion **122** via a channel in the second central portion **124**.

Referring to FIG. 10, a particular illustrative embodiment of a method **1000** of fabricating a vertical tunnel field effect transistor device is shown. The method **1000** of FIG. 10 may be performed to fabricate embodiments of the vertical TFET devices depicted in FIGS. 1-9.

The method **1000** includes forming a well region, a base portion, a central portion, and a top portion within a substrate, at **1002**. For example, in FIG. 3, n-type implantation may be performed in the substrate **102** to create the first well region **104**. After the first well region **104** is formed in the substrate **102**, the first base portion **112** may be formed in the first well region **104** using ion implantation **304**. For example, P+ implantation may be performed in the first well region **104** to create the first base portion **112**. The first base portion **112** may protrude from a surface of the first well region **104**. After the first base portion **112** is formed in the first well region **104**, the first central portion **114** may be formed on top of the first base portion **112** using ion implantation **304**. For example, P- implantation may be performed in the substrate **102** and on top of the first base portion **112** to create the first central portion **114**. After the first central portion **114** is formed on the first base portion **112**, the first top portion **116** may be formed on top of the first central portion **114** using ion implantation **304**. For example, N+ implantation may be performed in the substrate **102** and on top of the first central portion **114** to create the first top portion **116**.

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A vertical fin structure may be etched, at **1004**. For example, in FIG. 5, the hard mask films **530**, **540** may be patterned on top of the first top portion **116** and the second top portion **126**, respectively, to protect areas beneath the hard mask films **530**, **540** during etching. After patterning the hard mask film **530**, the first fin structure may be etched. For example, areas that are not protected by the hard mask films **530**, **540** may be etched down to the well regions **104**, **106**. The remaining areas that are protected (e.g., underneath) the hard mask films **530**, **540** may correspond to the first vertical fin structure.

A shallow trench isolation (STI) oxide layer may be formed between the vertical fin structure and a second vertical fin structure, at **1006**. For example, in FIG. 6, the STI oxide film **108** may be formed between the structure corresponding to the first vertical TFET **110** and the structure corresponding to the second vertical TFET **120**. The STI oxide film **108** may be formed on top of the hard mask films **530**, **540** and on top of the top portions **116**, **126**. A CMP process for planarization may be performed until the hard mask films **530**, **540** are reached. A recess etch may be performed and the hard mask films **530**, **540** may be removed. The STI oxide layer **108** may be located on top of the surface **103** and between the base portions **112**, **122** to isolate the vertical TFETs **110**, **120**.

A dielectric layer may be deposited on the vertical fin structure, at **1008**. For example, in FIG. 7, the material having the high dielectric constant (k) may be deposited on the first fin structure. The first pair of sidewalls **117** may correspond to a dielectric layer. A first gate material may be deposited on the dielectric layer, at **1010**. For example, in FIG. 7, the first gate material **718** (e.g., poly-silicon) may be deposited and patterned around the first pair of sidewalls **117**.

In a particular embodiment, the method **1000** may include patterning a photoresist on the substrate prior to implanting the well region, the base portion, the central portion, and the top portion. For example, referring to FIG. 3, the first photoresist **302** is patterned on top of the substrate **102**. For example, the first photoresist **302** may be patterned to select (e.g., expose) a particular area of the substrate **102** to implant the first vertical TFET **110**. After patterning the first photoresist **302**, the first vertical TFET **110** may be implanted.

In a particular embodiment, the method **1000** may include depositing a hard mask film on the top portion. For example, referring to FIG. 5, the first hard mask film **530** may be deposited on top of the first top portion **116** and the substrate **102**, and the second hard mask film **540** may be deposited on top of the second top portion **126** and the substrate **102**. In a particular embodiment, the first hard mask film **530** and the second hard mask film **540** may be a single hard mask film deposited across the top of the vertical TFET device illustrated in FIG. 4 after the second photoresist **402** is removed.

In a particular embodiment, the method **1000** may include patterning the hard mask film prior to etching the vertical fin structure from the substrate. For example, referring to FIG. 5, the hard mask films **530**, **540** may be patterned on top of the first top portion **116** and the second top portion **126**, respectively, to protect areas beneath the hard mask films **530**, **540** during etching. After patterning the hard mask films **530**, **540**, the first fin structure and the second fin structure may be etched. For example, areas that are not protected by the hard mask films **530**, **540** may be etched down to the well regions **104**, **106**.

In a particular embodiment, the method **1000** may include forming an oxide layer. For example, referring to FIG. 6, the STI oxide layer **108** may be deposited on the substrate **102** (on the well regions **104**, **106** and on the particular areas of the base portions **112**, **122** that are not protected by the hard mask

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films **530**, **540**). The STI oxide layer **108** may be polished using a chemical and mechanical polishing (CMP) process and etched. After the STI oxide layer **108** is etched, the hard mask films **530**, **540** may be removed.

In a particular embodiment, the method **1000** may include depositing an inter-layer dielectric oxide on the first gate material. For example, referring to FIG. 8, the inter-layer dielectric oxide **850** may be deposited on the first gate material **718** and on the STI oxide layer **108**. After depositing the inter-layer dielectric oxide **850**, a CMP process is performed on the inter-layer dielectric oxide **850** to smooth the surface of the inter-layer dielectric oxide **850**.

In a particular embodiment, the method **1000** may include removing the first gate material and depositing a gate metal. For example, referring to FIG. 8, the first gate material **718** may be removed and an n-type metal gate may be deposited to create the first gate **118**. The second gate material **728** may also be removed and a p-type metal gate may be deposited to create the second gate **128**.

As a result, the first central portion **114** and the second central portion **124** may permit the formation of band-to-band tunneling currents in channels, where the lengths (L) of the channels are independent of the width of the gates **118**, **128**. The gates **118**, **128** may be independently designed and/or adjusted to manage an amount of saturation current supported by the vertical TFETs **110**, **120** without affecting the length (L) of the channels. The height of the central portions **114**, **124** (e.g., the channel lengths) may also be designed independently of a lithography process used for designing the gates. For example, because the channel is vertical (as opposed to planar), the channel is not limited to a region or a location that is under a planar gate of a field effect transistor.

Referring to FIG. 11, a block diagram of a particular illustrative embodiment of a wireless communication device is depicted and generally designated **1100**. The device **1100** includes a processor **1110**, such as a digital signal processor (DSP), coupled to a memory **1132** (e.g., a random access memory (RAM), flash memory, read-only memory (ROM), programmable read-only memory (PROM), erasable programmable read-only memory (EPROM), electrically erasable programmable read-only memory (EEPROM), registers, hard disk, a removable disk, a compact disc read-only memory (CD-ROM), or any other form of non-transient storage medium known in the art). The memory **1132** may store instructions **1162** that are executable by the processor **1110**. The memory **1132** may store data **1166** that is accessible to the processor **1110**.

The device **1100** includes a vertical tunnel field effect transistor device **1148**. In an illustrative embodiment, the vertical tunnel field effect transistor device **1148** may correspond to the vertical tunnel field transistor devices depicted in FIGS. 1-9. The vertical tunnel field effect transistor device **118** may be used to form logic circuits in the processor **1110**, other components (e.g., the display controller **1126**, the wireless controller **1140**, and/or a coder/decoder (CODEC) **1126**) of the device **1100**, or any combination thereof. In a particular embodiment, the logic circuits may be used for power conservation techniques. FIG. 11 also shows a display controller **1126** that is coupled to the processor **1110** and to a display **1128**. The CODEC **1134** may also be coupled to the processor **1110**. A speaker **1136** and a microphone **1138** may be coupled to the CODEC **1134**. FIG. 11 also indicates that a wireless controller **1140** may be coupled to the processor **1110** and may be further coupled to an antenna **1142** via the RF interface **1152**.

In a particular embodiment, the processor **1110**, the display controller **1126**, the memory **1132**, the CODEC **1134**, and the

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wireless controller **1140** are included in a system-in-package or system-on-chip device **1122**. In a particular embodiment, an input device **1130** and a power supply **1144** are coupled to the system-on-chip device **1122**. Moreover, in a particular embodiment, as illustrated in FIG. 11, the display **1128**, the input device **1130**, the speaker **1136**, the microphone **1138**, the antenna **1142**, and the power supply **1144** are external to the system-on-chip device **1122**. However, each of the display **1128**, the input device **1130**, the speaker **1136**, the microphone **1138**, the wireless antenna **1142**, and the power supply **1144** may be coupled to a component of the system-on-chip device **1122**, such as an interface or a controller.

The foregoing disclosed devices and functionalities may be designed and configured into computer files (e.g., RTL, GDSII, GERBER, etc.) stored on computer readable media. Some or all such files may be provided to fabrication handlers who fabricate devices based on such files. Resulting products include semiconductor wafers that are then cut into semiconductor die and packaged into a semiconductor chip. The semiconductor chips are then integrated into electronic devices, as described further with reference to FIG. 12.

Referring to FIG. 12, a particular illustrative embodiment of an electronic device manufacturing process is depicted and generally designated **1200**. Physical device information **1202** is received at the manufacturing process **1200**, such as at a research computer **1206**. The physical device information **1202** may include design information representing at least one physical property of a semiconductor device, such as a vertical tunnel field effect transistor device (e.g., the vertical tunnel field effect transistor devices illustrated in FIGS. 1-9 and/or a vertical tunnel field effect transistor device formed according to the method **1000** of FIG. 10). For example, the physical device information **1202** may include physical parameters, material characteristics, and structure information that is entered via a user interface **1204** coupled to the research computer **1206**. The research computer **1206** includes a processor **1208**, such as one or more processing cores, coupled to a computer readable medium such as a memory **1210**. The memory **1210** may store computer readable instructions that are executable to cause the processor **1208** to transform the physical device information **1202** to comply with a file format and to generate a library file **1212**.

In a particular embodiment, the library file **1212** includes at least one data file including the transformed design information. For example, the library file **1212** may include a library of devices including a vertical tunnel field effect transistor device (e.g., the vertical tunnel field effect transistor devices illustrated in FIGS. 1-9 and/or a vertical tunnel field effect transistor device formed according to the method **1000** of FIG. 10) provided for use with an electronic design automation (EDA) tool **1220**.

The library file **1212** may be used in conjunction with the EDA tool **1220** at a design computer **1214** including a processor **1216**, such as one or more processing cores, coupled to a memory **1218**. The EDA tool **1220** may be stored as processor executable instructions at the memory **1218** to enable a user of the design computer **1214** to design a vertical tunnel field effect transistor device (e.g., the vertical tunnel field effect transistor devices illustrated in FIGS. 1-9 and/or a vertical tunnel field effect transistor device formed according to the method **1000** of FIG. 10) using the library file **1212**. For example, a user of the design computer **1214** may enter circuit design information **1222** via a user interface **1224** coupled to the design computer **1214**. The circuit design information **1222** may include design information representing at least one physical property of a vertical tunnel field effect transistor device (e.g., the vertical tunnel field effect transistor

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devices illustrated in FIGS. 1-9 and/or a vertical tunnel field effect transistor device formed according to the method **1000** of FIG. 10). To illustrate, the circuit design property may include identification of particular circuits and relationships to other elements in a circuit design, positioning information, feature size information, interconnection information, or other information representing a physical property of a semiconductor device.

The design computer **1214** may be configured to transform the design information, including the circuit design information **1222**, to comply with a file format. To illustrate, the file formation may include a database binary file format representing planar geometric shapes, text labels, and other information about a circuit layout in a hierarchical format, such as a Graphic Data System (GDSII) file format. The design computer **1214** may be configured to generate a data file including the transformed design information, such as a GDSII file **1226** that includes information describing a vertical tunnel field effect transistor device (e.g., the vertical tunnel field effect transistor devices illustrated in FIGS. 1-9 and/or a vertical tunnel field effect transistor device formed according to the method **1000** of FIG. 10) in addition to other circuits or information. To illustrate, the data file may include information corresponding to a system-on-chip (SOC) that includes a vertical tunnel field effect transistor device (e.g., the vertical tunnel field effect transistor devices illustrated in FIGS. 1-9 and/or a vertical tunnel field effect transistor device formed according to the method **1000** of FIG. 10), and that also includes additional electronic circuits and components within the SOC.

The GDSII file **1226** may be received at a fabrication process **1228** to manufacture a vertical tunnel field effect transistor device (e.g., the vertical tunnel field effect transistor devices illustrated in FIGS. 1-9 and/or a vertical tunnel field effect transistor device formed according to the method **1000** of FIG. 10), according to transformed information in the GDSII file **1226**. For example, a device manufacture process may include providing the GDSII file **1226** to a mask manufacturer **1230** to create one or more masks, such as masks to be used with photolithography processing, illustrated as a representative mask **1232**. The mask **1232** may be used during the fabrication process to generate one or more wafers **1234**, which may be tested and separated into dies, such as a representative die **1236**. The die **1236** includes a vertical tunnel field effect transistor device (e.g., the vertical tunnel field effect transistor devices illustrated in FIGS. 1-9 and/or a vertical tunnel field effect transistor device formed according to the method **1000** of FIG. 10).

In conjunction with the described embodiments, a non-transitory computer-readable medium stores instructions executable by a computer to perform the method **1000** of FIG. 10. For example, equipment of a semiconductor manufacturing plant may include a computer and a memory and may perform the method **1000** of FIG. 10, such as in connection with the fabrication process **1228** and using the GDSII file **1226**. To illustrate, the computer may execute instructions to initiate fabrication of a vertical tunnel field effect transistor, as described with reference to FIGS. 2-8.

The die **1236** may be provided to a packaging process **1238** where the die **1236** is incorporated into a representative package **1240**. For example, the package **1240** may include the single die **1236** or multiple dies, such as a system-in-package (SiP) arrangement. The package **1240** may be configured to conform to one or more standards or specifications, such as Joint Electron Device Engineering Council (JEDEC) standards.

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Information regarding the package **1240** may be distributed to various product designers, such as via a component library stored at a computer **1246**. The computer **1246** may include a processor **1248**, such as one or more processing cores, coupled to a memory **1250**. A printed circuit board (PCB) tool may be stored as processor executable instructions at the memory **1250** to process PCB design information **1242** received from a user of the computer **1246** via a user interface **1244**. The PCB design information **1242** may include physical positioning information of a packaged semiconductor device on a circuit board, the packaged semiconductor device corresponding to the package **1240** including a vertical tunnel field effect transistor device (e.g., the vertical tunnel field effect transistor devices illustrated in FIGS. **1-9** and/or a vertical tunnel field effect transistor device formed according to the method **1000** of FIG. **10**).

The computer **1246** may be configured to transform the PCB design information **1242** to generate a data file, such as a GERBER file **1252** with data that includes physical positioning information of a packaged semiconductor device on a circuit board, as well as layout of electrical connections such as traces and vias, where the packaged semiconductor device corresponds to the package **1240** including a vertical tunnel field effect transistor device (e.g., the vertical tunnel field effect transistor devices illustrated in FIGS. **1-9** and/or a vertical tunnel field effect transistor device formed according to the method **1000** of FIG. **10**). In other embodiments, the data file generated by the transformed PCB design information may have a format other than a GERBER format.

The GERBER file **1252** may be received at a board assembly process **1254** and used to create PCBs, such as a representative PCB **1256**, manufactured in accordance with the design information stored within the GERBER file **1252**. For example, the GERBER file **1252** may be uploaded to one or more machines to perform various steps of a PCB production process. The PCB **1256** may be populated with electronic components including the package **1240** to form a representative printed circuit assembly (PCA) **1258**.

The PCA **1258** may be received at a product manufacture process **1260** and integrated into one or more electronic devices, such as a first representative electronic device **1262** and a second representative electronic device **1264**. As an illustrative, non-limiting example, the first representative electronic device **1262**, the second representative electronic device **1264**, or both, may be selected from the group of a cellular phone, a wireless local area network (LAN) device, a set top box, a music player, a video player, an entertainment unit, a navigation device, a communications device, a personal digital assistant (PDA), a fixed location data unit, and a computer, into which a vertical tunnel field effect transistor device (e.g., the vertical tunnel field effect transistor devices illustrated in FIGS. **1-9** and/or a vertical tunnel field effect transistor device formed according to the method **1000** of FIG. **10**) is integrated. As another illustrative, non-limiting example, one or more of the electronic devices **1262** and **1264** may be remote units such as mobile phones, hand-held personal communication systems (PCS) units, portable data units such as personal data assistants, global positioning system (GPS) enabled devices, navigation devices, fixed location data units such as meter reading equipment, or any other device that stores or retrieves data or computer instructions, or any combination thereof. Although FIG. **13** illustrates remote units according to teachings of the disclosure, the disclosure is not limited to these illustrated units. Embodiments of the disclosure may be suitably employed in any device which includes active integrated circuitry including memory and on-chip circuitry.

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A device that includes a vertical tunnel field effect transistor device (e.g., the vertical tunnel field effect transistor devices illustrated in FIGS. **1-9** and/or a vertical tunnel field effect transistor device formed according to the method **1000** of FIG. **10**) may be fabricated, processed, and incorporated into an electronic device, as described in the illustrative process **1200**. One or more aspects of the embodiments disclosed with respect to FIGS. **1-11** may be included at various processing stages, such as within the library file **1212**, the GDSII file **1226**, and the GERBER file **1252**, as well as stored at the memory **1210** of the research computer **1206**, the memory **1218** of the design computer **1214**, the memory **1250** of the computer **1246**, the memory of one or more other computers or processors (not shown) used at the various stages, such as at the board assembly process **1254**, and also incorporated into one or more other physical embodiments such as the mask **1232**, the die **1236**, the package **1240**, the PCA **1258**, other products such as prototype circuits or devices (not shown), or any combination thereof. Although various representative stages are depicted with reference to FIGS. **1-11** to fabricate a vertical tunnel field effect transistor device, in other embodiments fewer stages may be used or additional stages may be included. Similarly, the process **1200** of FIG. **12** may be performed by a single entity or by one or more entities performing various stages of the process **1200**.

In conjunction with the described embodiments, an apparatus includes means for providing charge carriers to a tunneling region. For example, the means for providing the charge carriers may include the first base portion **112**, the first top portion **116**, the second base portion **122**, and the second top portion **126** depicted in FIGS. **1-9**.

The apparatus may also include means for receiving the charge carriers from the tunneling region. For example, the means for receiving the charge carriers may include the first base portion **112**, the first top portion **116**, the second base portion **122**, and the second top portion **126** depicted in FIGS. **1-9**.

The apparatus may also include means for biasing the tunneling channel to enable band-to-band tunneling at the tunneling channel. For example, the means for biasing the tunneling channel may include the contacts **902-912** of FIG. **9**, the voltages applied to the contacts **902-912** of FIG. **9**, the processor **1110** of FIG. **10**, or any combination thereof.

Those of skill would further appreciate that the various illustrative logical blocks, configurations, modules, circuits, and algorithm steps described in connection with the embodiments disclosed herein may be implemented as electronic hardware, computer software executed by a processor, or combinations of both. Various illustrative components, blocks, configurations, modules, circuits, and steps have been described above generally in terms of their functionality. Whether such functionality is implemented as hardware or processor executable instructions depends upon the particular application and design constraints imposed on the overall system. Skilled artisans may implement the described functionality in varying ways for each particular application, but such implementation decisions should not be interpreted as causing a departure from the scope of the present disclosure.

The steps of a method or algorithm described in connection with the embodiments disclosed herein may be embodied directly in hardware, in a software module executed by a processor, or in a combination of the two. A software module may reside in random access memory (RAM), flash memory, read-only memory (ROM), programmable read-only memory (PROM), erasable programmable read-only memory (EPROM), electrically erasable programmable read-only memory (EEPROM), registers, hard disk, a remov-

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able disk, a compact disc read-only memory (CD-ROM), or any other form of non-transient storage medium known in the art. An exemplary storage medium is coupled to the processor such that the processor may read information from, and write information to, the storage medium. In the alternative, the storage medium may be integral to the processor. The processor and the storage medium may reside in an application-specific integrated circuit (ASIC). The ASIC may reside in a computing device or a user terminal. In the alternative, the processor and the storage medium may reside as discrete components in a computing device or user terminal.

The previous description of the disclosed embodiments is provided to enable a person skilled in the art to make or use the disclosed embodiments. Various modifications to these embodiments will be readily apparent to those skilled in the art, and the principles defined herein may be applied to other embodiments without departing from the scope of the disclosure. Thus, the present disclosure is not intended to be limited to the embodiments shown herein but is to be accorded the widest scope possible consistent with the principles and novel features as defined by the following claims.

What is claimed is:

1. A tunnel field effect transistor (TFET) device comprising:

a fin structure comprising:

a base portion having a portion disposed in a recess of a substrate and protruding through a plane of a surface of the substrate;

a top portion;

a pair of sidewalls extending from a part of the base portion to the top portion;

a first doped region having a first dopant concentration at the base portion; and

a second doped region having a second dopant concentration at the top portion; and

a gate comprising a first conductive structure neighboring a first sidewall of the pair of sidewalls; and

a dielectric layer that electrically isolates the first conductive structure from the first sidewall.

2. The TFET device of claim 1, wherein the gate further comprises a second conductive structure neighboring a second sidewall of the pair of sidewalls, wherein the dielectric layer electrically isolates the second conductive structure from the second sidewall.

3. The TFET device of claim 2, wherein the gate further comprises a third conductive structure neighboring the top portion, wherein the dielectric layer electrically isolates the third conductive structure from the top portion, and wherein the third conductive structure is coupled to the first conductive structure and to the second conductive structure.

4. The TFET device of claim 1, wherein the fin structure further comprises a central portion between the base portion and the top portion.

5. The TFET device of claim 1, wherein the base portion, the top portion, and a central portion between the base portion and the top portion are comprised of a first type of material.

6. The TFET device of claim 1, wherein at least one of the base portion, the top portion, and a central portion between the base portion and the top portion comprises silicon.

7. The TFET device of claim 1, wherein:

the top portion comprises an upper surface that is parallel to the surface of the substrate and is adjacent to another conductive structure of the gate, and

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a central portion between the base portion and the top portion corresponds to a channel region of the fin structure.

8. The TFET device of claim 1, wherein:

a central portion between the base portion and the top portion corresponds to a channel region of the fin structure, and

a channel length corresponds to a height of the central portion.

9. The TFET device of claim 1, wherein a saturation current is adjusted by changing a width of the gate.

10. The TFET device of claim 1, wherein the base portion corresponds to a drain of the fin structure and the top portion corresponds to a source of the fin structure.

11. The TFET device of claim 10, wherein the first dopant concentration includes an n-type concentration and the second dopant concentration includes a p-type concentration.

12. The TFET device of claim 10, wherein the first dopant concentration includes a p-type concentration and the second dopant concentration includes an n-type concentration.

13. The TFET device of claim 1, wherein the first doped region comprises a first material and the second doped region comprises a second material, and wherein the first material is different from the second material.

14. The TFET device of claim 1, wherein the base portion corresponds to a source of the fin structure and the top portion corresponds to a drain of the fin structure.

15. The TFET device of claim 14, wherein the first dopant concentration includes an n-type concentration and the second dopant concentration includes a p-type concentration.

16. The TFET device of claim 14, wherein the first dopant concentration includes a p-type concentration and the second dopant concentration includes an n-type concentration.

17. The TFET device of claim 1, integrated into at least one semiconductor die.

18. The TFET device of claim 1, integrated into a device selected from the group consisting of a communications device, a personal digital assistant (PDA), a navigation device, a fixed location data unit, a set top box, a music player, a video player, an entertainment unit, and a computer.

19. An apparatus comprising:

means for providing charge carriers to a tunneling channel; means for receiving the charge carriers from the tunneling channel, wherein one of the means for providing or the means for receiving is at a base portion of a fin structure and is adjacent to a substrate surface, the base portion having a portion disposed in a recess of a substrate and protruding through a plane of a surface of the substrate, and wherein the other of the means for providing or the means for receiving is at a top portion of the fin structure; and

means for biasing the tunneling channel to enable band-to-band tunneling at the tunneling channel.

20. The apparatus of claim 19, wherein the means for providing includes a source of the fin structure.

21. The apparatus of claim 19, wherein the means for receiving includes a drain of the fin structure.

22. The apparatus of claim 19, further comprising a device selected from the group consisting of a set top box, a music player, a video player, an entertainment unit, a navigation device, a communications device, a personal digital assistant (PDA), a fixed location data unit, and a computer, into which the means for providing, the means for receiving, and the means for biasing are integrated.

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